

SILICON PHOTONIC INTEGRATED CHIP DEVICE AND FABRICATING METHOD THEREFOR

Abstract

5 The present invention relates to a silicon photonic integrated chip (PIC) device, comprising a silicon-on-insulator (SOI) substrate (11), an optical waveguide, a suspended edge coupler (12) and a protective film (13). The SOI substrate (11) serves as a platform on the device is fabricated. The optical waveguide is disposed on the SOI substrate (11) for guiding light waves. The suspended edge coupler
10 (12) couples the light waves between the waveguide and an optical fiber. The protective film (13) protects the device (10) from any external environmental conditions. A method for fabricating the device is also disclosed.

Most illustrative drawing: Figure 1